

SOT616-4

plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN24
Package type industry code	HVQFN24
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-220
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	6-3-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.9	-	4	4.1	mm
E	package width		3.9	-	4	4.1	mm
A	seated height		0.8	-	0.85	0.9	mm
A ₂	package height		[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination		-	-	24	-	



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2. Package outline

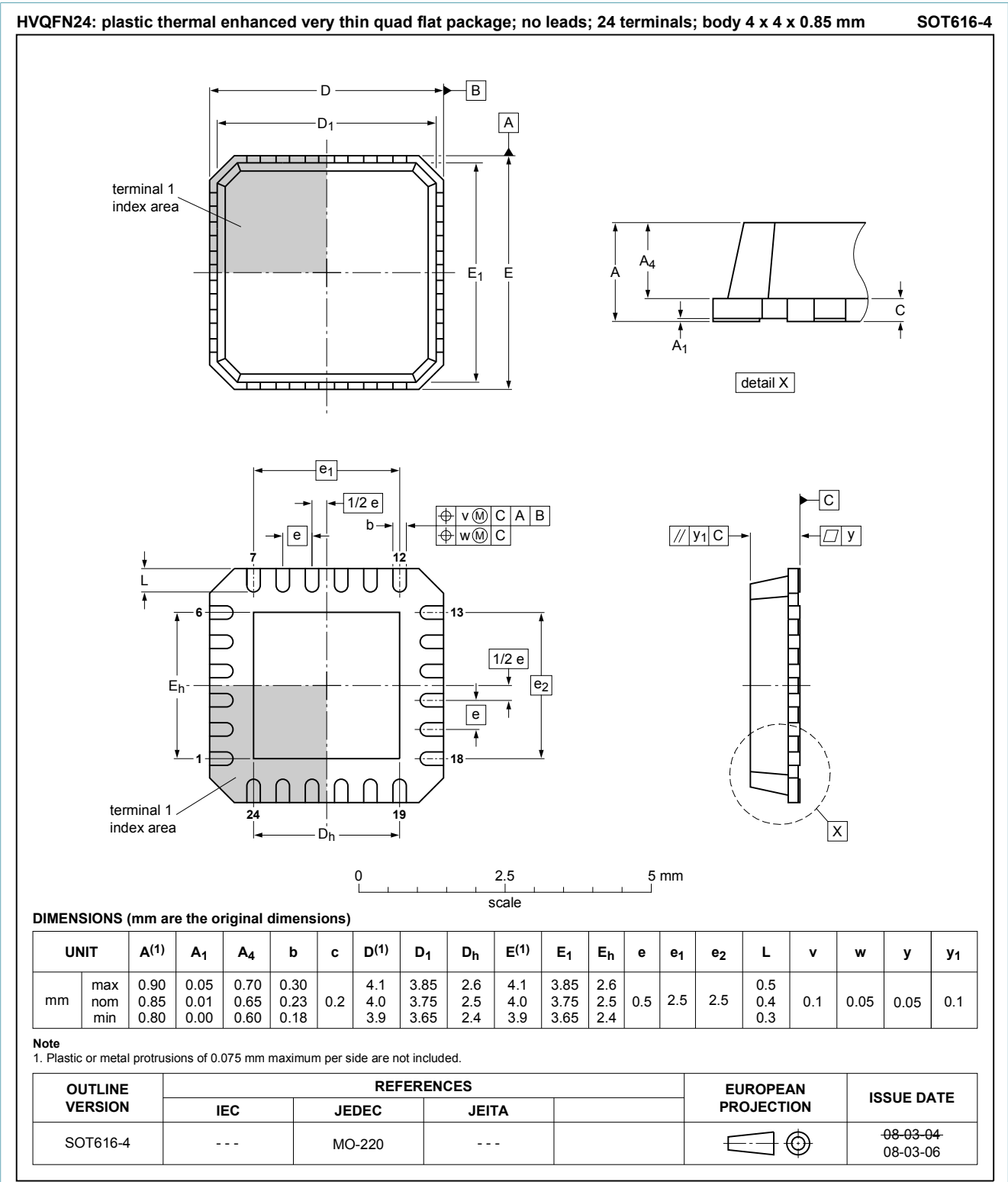


Fig. 1. Package outline HVQFN24 (SOT616-4)

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3. Legal information

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